

SILICON PHOTONIC: PDK AND EDA TOOLS

June 4th, 2019

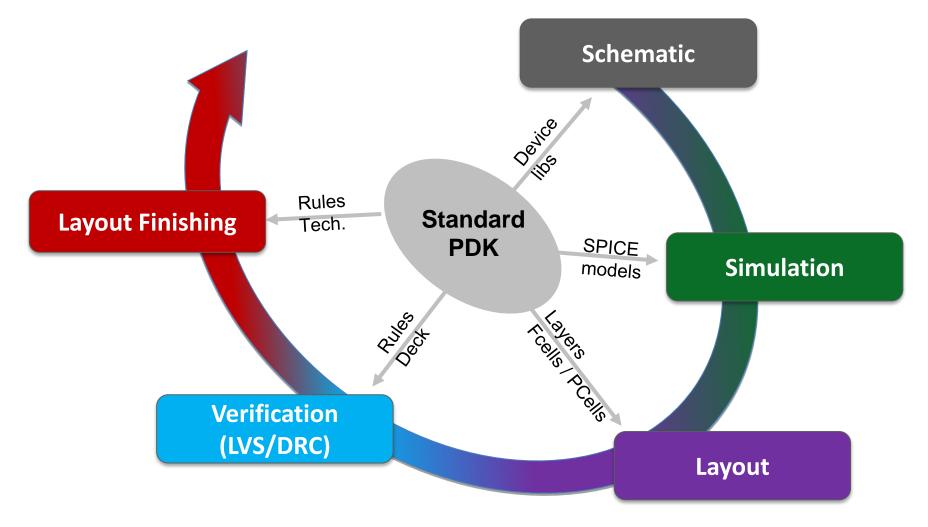
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- PDK environment for Si photonic technologies
- Simulation of photonic integrated circuits
- Silicon photonic device models
- Example of simulations
- Layout of photonic integrated circuits
- Conclusion

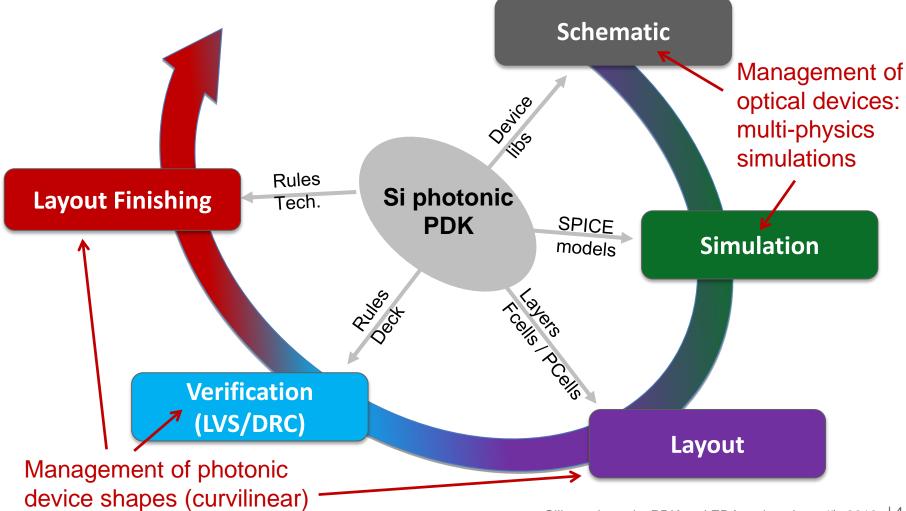


Overview of standard PDK environment





• Overview of our photonic design flow (CMOS-like)





• EDA tools for Si photonic: various existing CAD tools



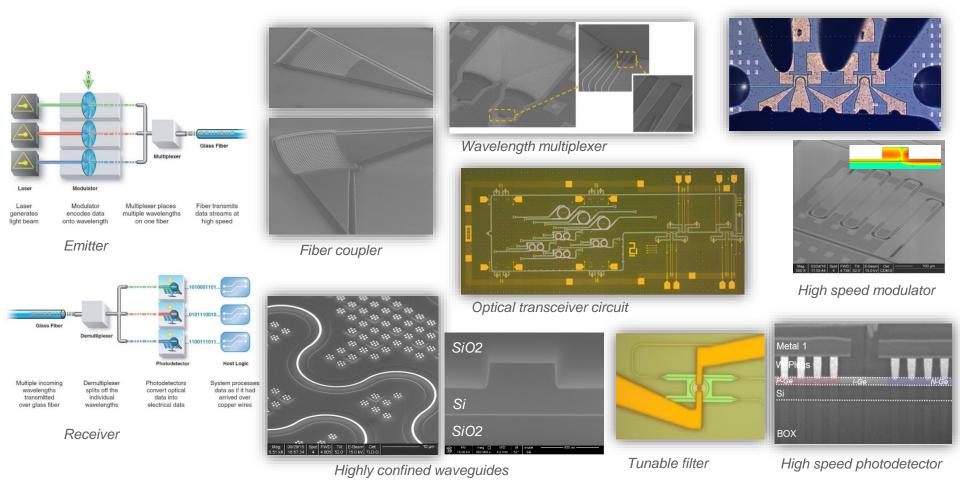
IC design requires multi-physics optimization using dedicated software

Our approach is an adaptation of standard EDA tools for photonic applications



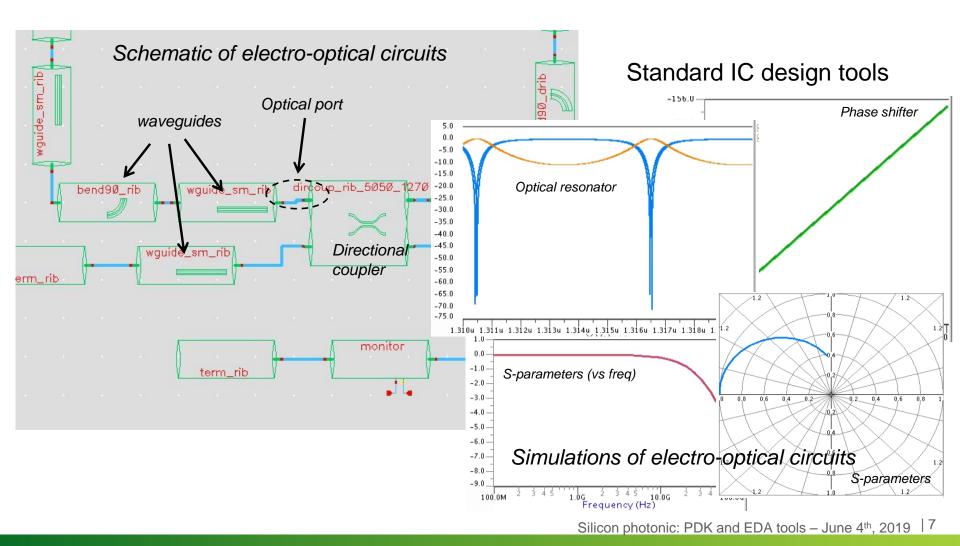
SIMULATION OF PHOTONIC INTEGRATED CIRCUITS

• Devices in Si photonic circuits



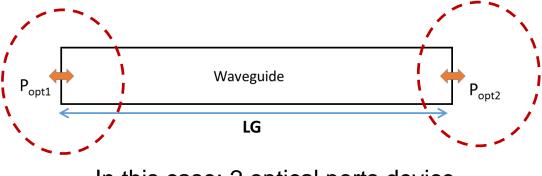


• Electro-optical co-optimization: schematic to simulation



SIMULATION OF PHOTONIC INTEGRATED CIRCUITS

Introduction to the optical bus: optical fields



In this case: 2 optical ports device

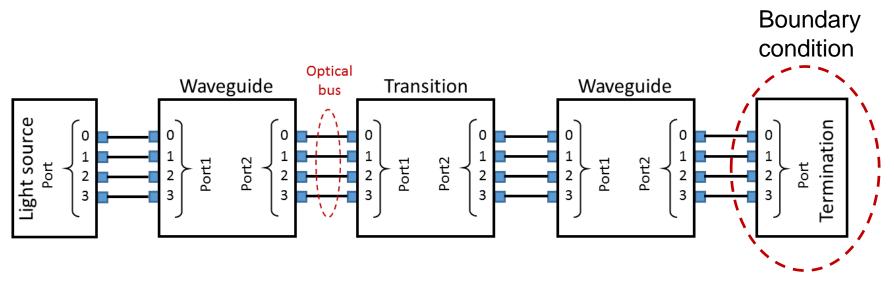
- Each optical port must be bi-directional because the position of the source light is unknown: symmetrical model topology
- Each port must contain information of module and phase of TM and TE fields: 4 analog values
- □ The wavelength information is managed as instance parameter



Introduction to the optical bus: optical fields

Each optical port consist to a bus of 4 nodes:

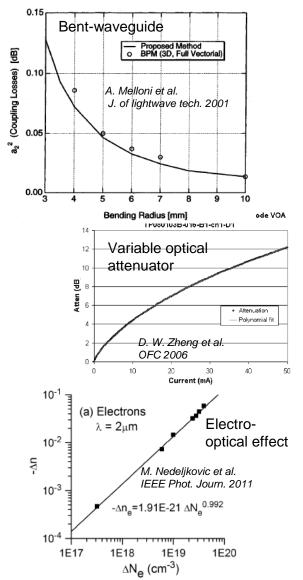
- Real part of the optical TE field
- Imaginary part of the optical TE field
- Real part of the optical TM field
- Imaginary part of the optical TM field





SILICON PHOTONIC DEVICE MODELS

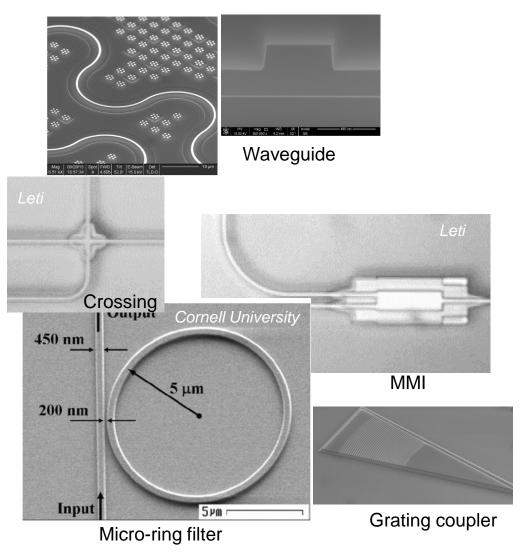
- SPICE modeling: major physical effects
 - Optical effects:
 - wave propagation (loss, phase shift) : waveguide
 - coupling effect: directional coupler, microring
 - □ split effect: Y-junction, interferometer
 - Thermo-optical effect: heater to change the group index
 - Thermo-electrical effect: thermal resistance and capacitance
 - Electro-optical effect: modulator using junction, photodetector





SILICON PHOTONIC DEVICE MODELS

- Passive devices
- Waveguides: straight, bent, S-bent, taper, transition, crossing, etc.
- Splitters: Y-junctions, multimode interferometers, directional couplers
- □ Filters: micro-ring resonators
- ❑ Optical IO: grating couplers

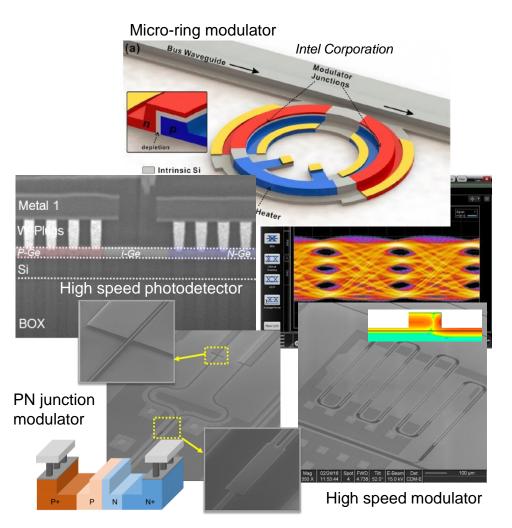


Passive devices are modeled by considering optical fields only



SILICON PHOTONIC DEVICES MODELS

- Active devices
 - Phase-shifter waveguide
 - Modulator: micro-ring, Mach-Zehnder modulator
 - Heater: tunable waveguide
 - Photodetector: Ge junction



Active devices are modeled by considering optical fields and electrical nodes



SILICON PHOTONIC DEVICES MODELS

• Photonic model suite (PMS) v1.0.0: Verilog-A codes

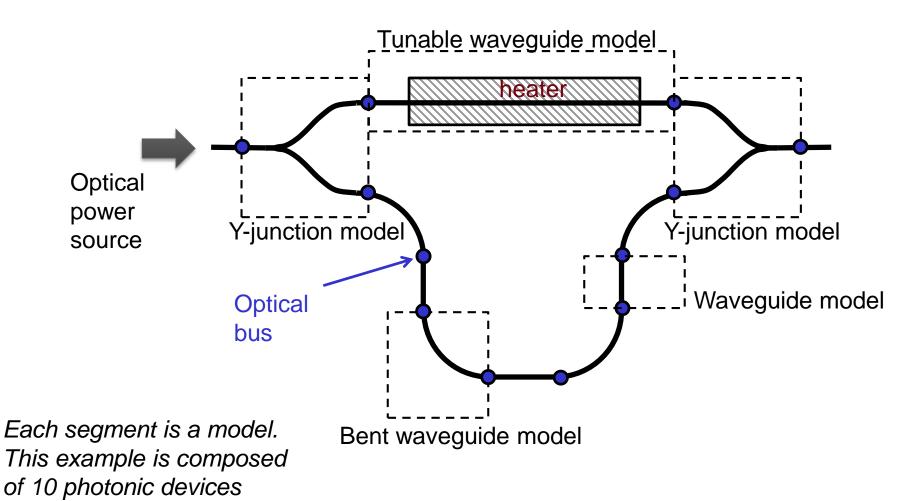
□ Wide-ranging set of models (22 models at present):

Model type	Device
Waveguides	Straight, bend, S-bend, transition, tapers, crossing, etc.
Splitters	Y-junction, directional coupler, multi-mode interferometers
I/O devices	Grating couplers
Filters	Micro-ring resonator
Active devices	Tunable waveguide, phase shifter, modulators, photodiodes
Tools	Voltage controlled light source, optical power monitoring

All IC simulators with the capability to manage Verilog-A models can use these models



• Example of basic circuit: Mach-Zehnder interferometer



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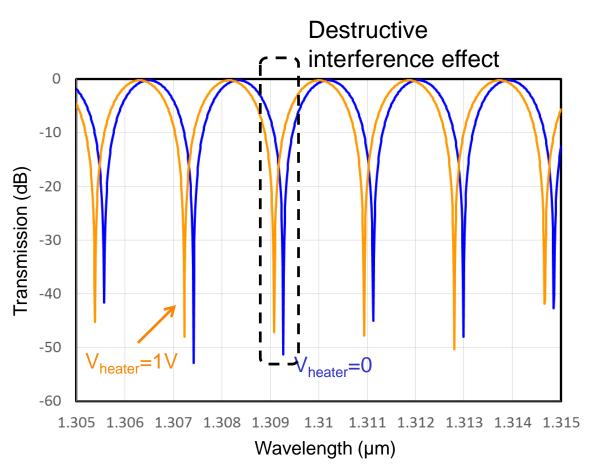


• Example of basic circuit: Mach-Zehnder interferometer

Interference effect: due to the length difference of the two optical paths (phase)

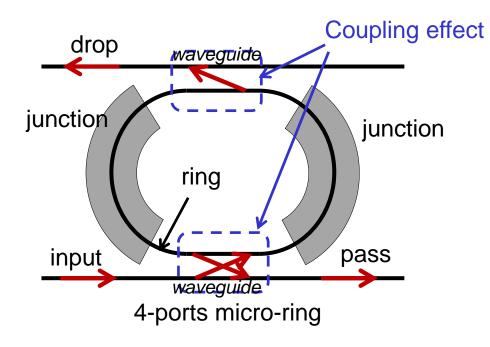
Biasing the heater, temperature increases: induces a phase variation to an optical path

Tunable destructive interference





• Example of SPICE model: micro-ring modulator

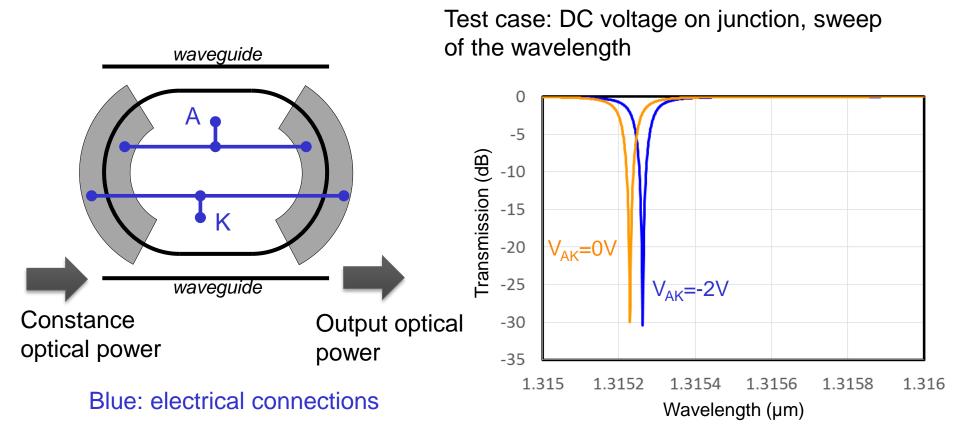


As example, 2 test cases:

- 1. Evaluation of the resonant wavelength
- 2. Simulation of the modulation effect

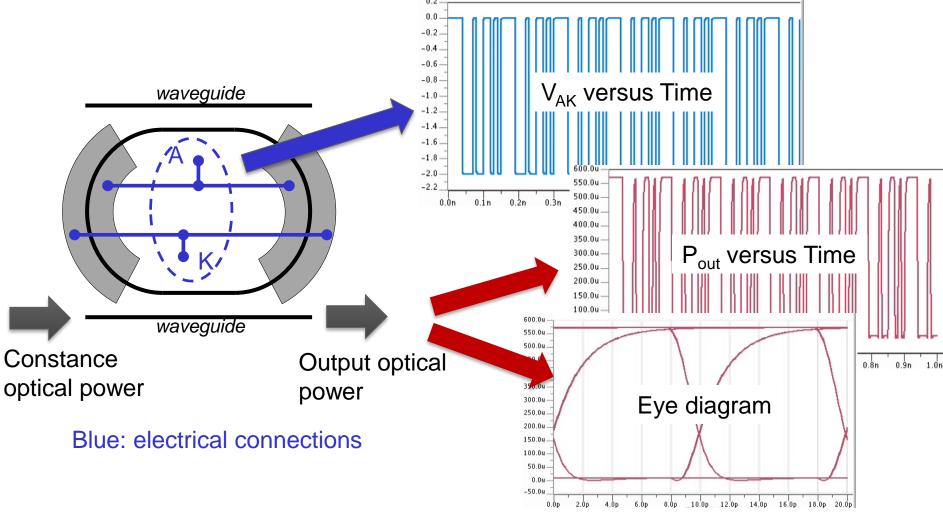


• Example of SPICE model: resonant wavelength of modulator



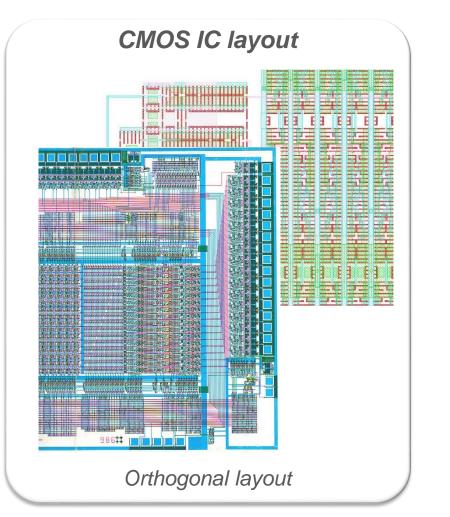


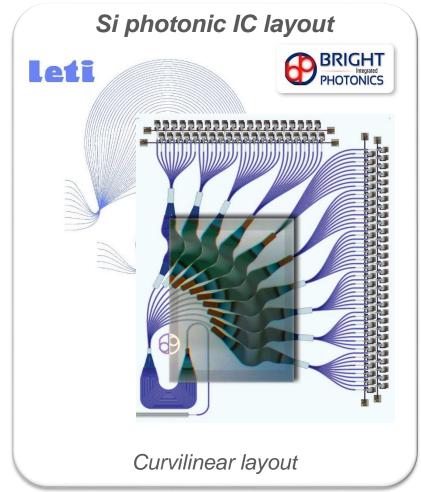
• Example of SPICE model: modulation effect





• CMOS IC design versus Si photonic IC design:

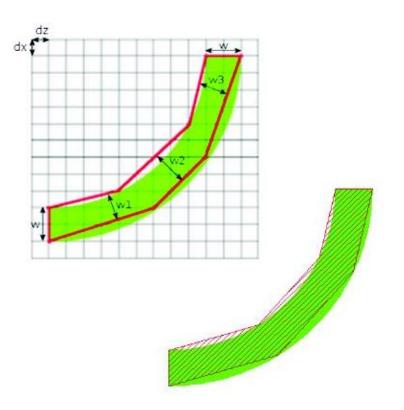




LAYOUT OF PHOTONIC INTEGRATED CIRCUITS

• Challenges:

- Skew edges are widely used to draw photonic layout component
- Layouts of photonic devices require dedicated methods to generate curvilinear and all angle designs
- The challenge is to control the discretization of all curvilinear shapes into polygons with the "snapping grid effect" constraint (~nm)

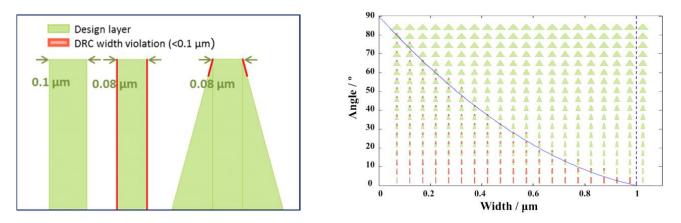




LAYOUT OF PHOTONIC INTEGRATED CIRCUITS

• Verification tools:

- LVS: the shapes of photonic devices are not compatible with existing tools. LVS requires dedicated markers for each device and extraction methodologies
- DRC: it must be adapted due to curvilinear design. Traditional IC DRC tools are incompatible with these geometries. It requires equation-based DRC (eqDRC)



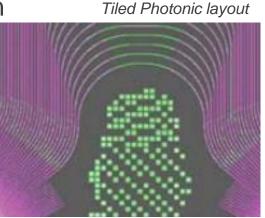
False error filtering with post-processing using additional geometrical information and user-defined criteria such as tolerance



• Layout finishing: dummies and Cad 2 Mask

□ Si photonic process requires to generate dummies

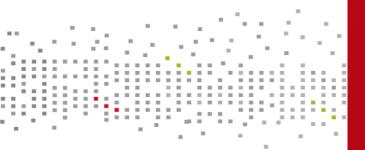
- Due to the shape of photonic devices: runtime for dummies generation is a significant issue (complex boundaries)
- New approach has been validated to address photonic layout specificities :
 - Post processing of photonic layers before sizing
 - Optimizing settings for hierarchy distribution
 - Tune the parallel processing on multi-CPU





- The use of standard IC design tools requires several significant developments.
- □ Schematic and models:
 - new models with their associated symbols for passive (waveguides, splitters, etc) and active (modulator) photonic devices.
 - Several physical effects must be included: wave propagation and phase shift, wave splits, electro-optical effects, temperature effects, heating effects, etc.
- Layout, verification and finishing: curvilinear shapes of photonic devices imply to introduce small grids in layout environment, equation-based DRC, additional layers for LVS.





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